REPLACEMENT SHEET

Title: Integration of Annealing Capability Into Metal Deposition or CMP Tool

1st Named Inventor: Jick M. Yu

Application No.: 10/810,735 Docket No. 42P6934D

WAFERS HAVING **METAL LAYERS DEPOSITED**

THEREON

METAL LAYER WAFER METAL LAYER WAFER

FIG. 7

WAFERS HAVING METAL LAYERS THAT HAVE BEEN **POLISHED**

POLISHED METAL LAYER	
WAFER	
POLISHED METAL LAYER	
WAFER	

FIG. 8